

Patent Abstracts of Japan

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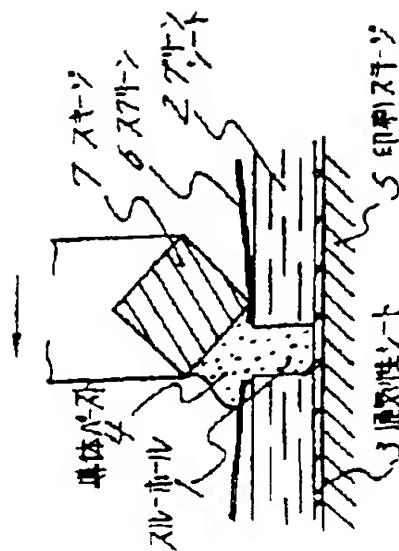
APPLICATION DATE : 14-01-91  
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APPLICANT : NEC CORP;

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TITLE : FILLING METHOD OF VIA OF  
THROUGH-HOLE



ABSTRACT : PURPOSE: To prevent insufficient conduction and to lower costs by filling conductive paste using a squeegee in a through-hole of a green sheet which is prevented from deforming by lining with a porous sheet.

CONSTITUTION: A porous sheet 3 is laminated on the rear side of a green sheet 2 with a through hole 1 to prevent deformation of the sheet 2. A porous sheet or a sheet formed by meshing fibers such as nylon is used as the sheet 3. The green sheet 2 is set to a print stage 5 and a screen 6 with a hole in a position corresponding to the through-hole 1 is laminated. A squeegee 7 is moved at a fixed speed on the screen 6 in arrow direction while carrying conductor paste 4 to charge the conductor paste 4 in the through hole 1. The sheet 3 removes excessive air inside the through hole 1 and prevents the conductor paste 4 from creeping and attaching. Thereby, it is possible to prevent insufficient conduction in vertical direction and to reduce costs.

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